MSKSEMI 美森科
SEMICONDUCTOR

ESD TVS TSS MOV GDT PLED

SK82B-MS THRU SK820B-MS

Product specification

SK82B-MS THRU SK820B-MS

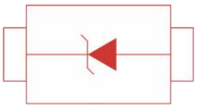
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction,majority carrier conduction
- Low power loss,high efficiency
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250 °C/10 seconds at terminals

MECHANICAL DATA

- Case : JEDEC DO-214AA/SMB molded plastic body
- Termina ls : Solderable per MIL-STD-750,Method 2026
- Polarity : Color band denotes cathode end Moun ting
- Pos ition : Any
- Weigh t : 0.0034 ounce, 0.1grams

Reference News

SMB(DO-214AA)	Schematic Diagram
	

Marking

SK82B-MS	SK84B-MS	SK86B-MS	SK810B-MS
SK82	SK84	SK86	SK810
SK812B-MS	**SK815B-MS**	**SK820B-MS**	
SK812	SK815	SK820	

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	SYMBOLS	SK82B -MS	SK84B -MS	SK86B -MS	SK810B -MS	SK812B -MS	SK815B -MS	SK820B -MS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	70	84	105	140	V
Maximum DC blocking voltage	V_{DC}	20	40	60	100	120	150	200	V
Maximum average forward rectified current	$I_{(AV)}$	8.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I_{FSM}	150							A
Maximum instantaneous forward voltage at 8.0A	V_F	0.45	0.55	0.70	0.85				V
Maximum DCreverse current at rated DCblocking voltage T_A=25℃ T_A=100℃	I_R	1.0 50							mA
Typical junction capacitance (1)	C_J	400		700					pF
Typical thermal resistance (2)	$R_{\theta JA}$	50							℃/W
Operating junction temperature range	T_J	-55 to +125							℃
Storage temperature range	T_{STG}	-55 to +150							℃

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 2.0x2.0”(5.0x5.0cm) copper pad areas

TypicalCharacterisitics

Fig.1 Forward Current Derating Curve

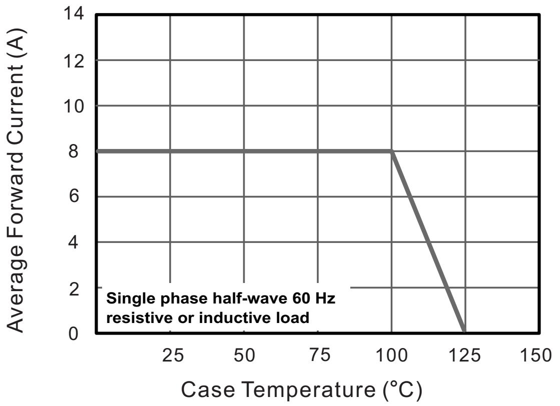


Fig.2 Typical Reverse Characteristics

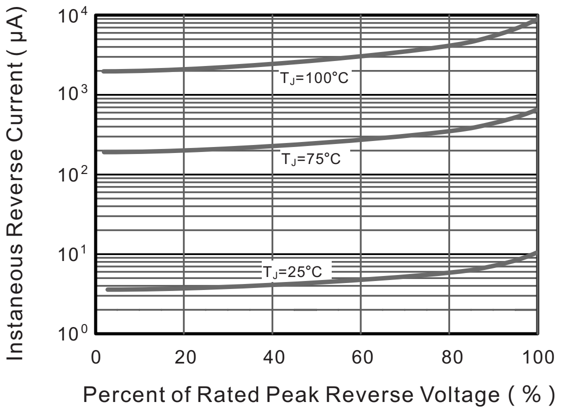


Fig.3 Typical Forward Characteristic

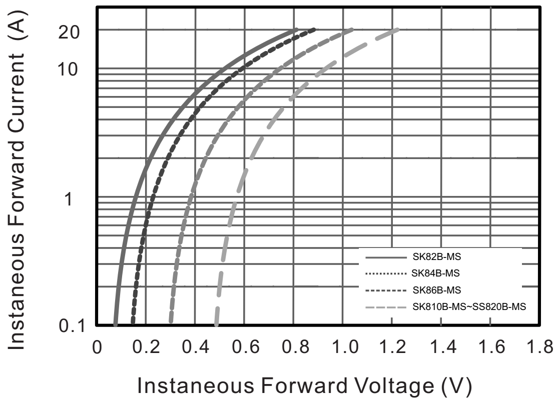


Fig.4 Typical Junction Capacitance

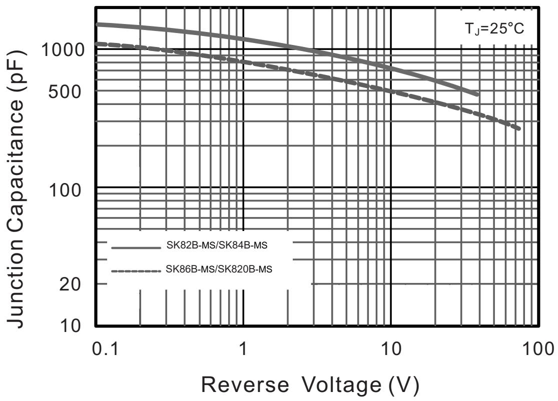


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

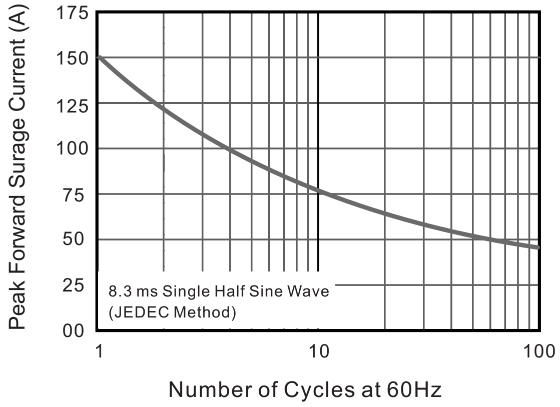
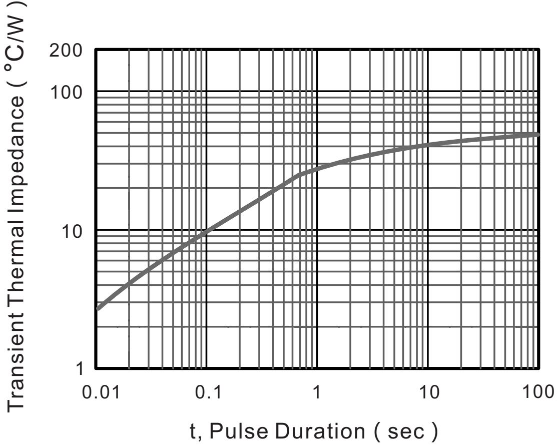
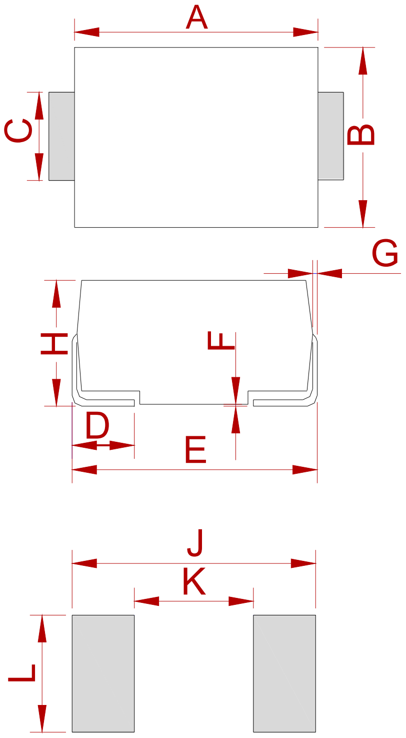


Fig.6- Typical Transient Thermal Impedance



PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

REEL SPECIFICATION

P/N	PKG	QTY
SK82B-MS THRU SK820B-MS	DO-214AA(SMB)	3000

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